

Chip Bead For EMI Suppression

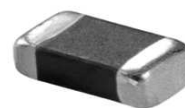
CIB/CIM21 Series (2012/ EIA 0805)

APPLICATION

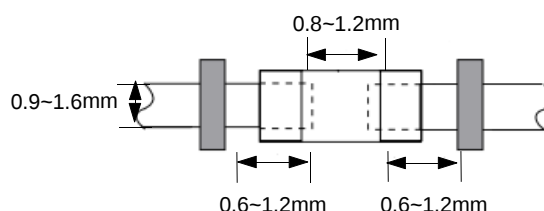
High frequency EMI prevention application to computers, printers, VCRs, TVs and mobile phones.

FEATURES

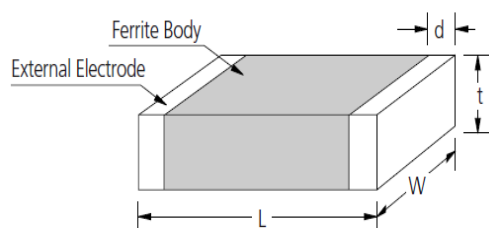
- Perfect shape for automatic mounting, with no directionality.
- Excellent solderability and high heat resistance for either flow or reflow soldering
- Monolithic inorganic material construction for high reliability
- Closed magnetic circuit configuration avoids crosstalk and is suitable for high density PCBs.



RECOMMENDED LAND PATTERN



DIMENSION



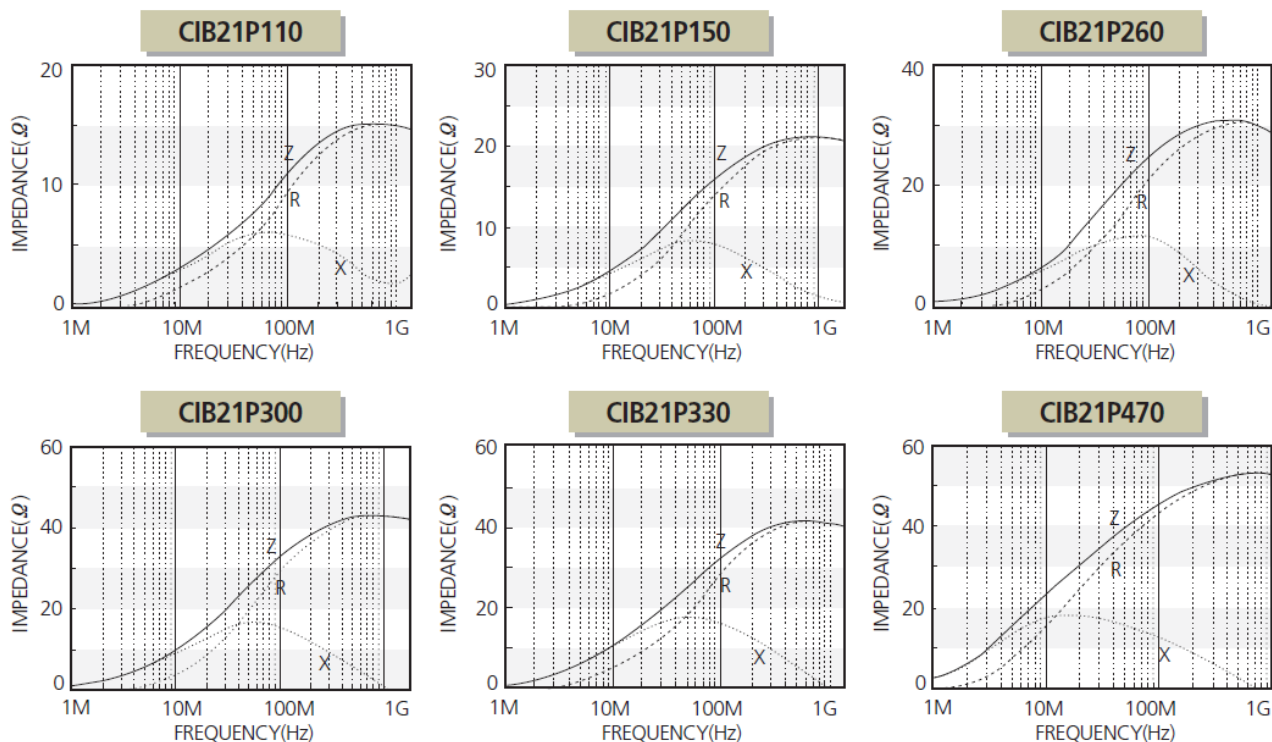
Type	Dimension [mm]			
	L	W	t	d
21	2.0±0.2	1.25±0.2	0.9±0.2	0.5+0.2 -0.3

DESCRIPTION

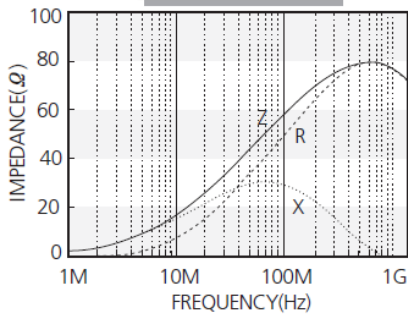
Part no.	Thickness (mm)	Impedance (Ω)±25%@100MHz	DC Resistance (Ω) Max.	Rated Current (mA) Max.
CIB21P110	0.9±0.2	11	0.01	2000
CIB21P150	0.9±0.2	15	0.01	2000
CIB21P260	0.9±0.2	26	0.01	2000
CIB21P300	0.9±0.2	30	0.05	2000
CIB21P330	0.9±0.2	33	0.05	1500
CIB21P470	0.9±0.2	47	0.05	1500
CIM21U600	0.9±0.2	60	0.08	900
CIM21U800	0.9±0.2	80	0.10	900
CIM21U101	0.9±0.2	100	0.10	800
CIM21U121	0.9±0.2	120	0.10	800
CIM21U151	0.9±0.2	150	0.15	600
CIM21U241	0.9±0.2	240	0.15	600
CIM21U301	0.9±0.2	300	0.15	500
CIM21U471	0.9±0.2	470	0.30	500
CIM21U601	0.9±0.2	600	0.30	500
CIM21U102	0.9±0.2	1000(at 70MHz)	0.40	500
CIM21U202	0.9±0.2	2000(at 70MHz)	0.70	300

Part no.	Thickness (mm)	Impedance (Ω) $\pm 25\%$ @100MHz	DC Resistance (Ω) Max.	Rated Current (mA) Max.
CIB21J260	0.9 $\pm$ 0.2	26	0.05	2000
CIB21J300	0.9 $\pm$ 0.2	30	0.05	2000
CIB21J400	0.9 $\pm$ 0.2	40	0.05	2000
CIM21J600	0.9 $\pm$ 0.2	60	0.08	900
CIM21J800	0.9 $\pm$ 0.2	80	0.08	1000
CIM21J121	0.9 $\pm$ 0.2	120	0.15	800
CIM21J151	0.9 $\pm$ 0.2	150	0.15	500
CIM21J221	0.9 $\pm$ 0.2	220	0.20	500
CIM21J241	0.9 $\pm$ 0.2	240	0.20	500
CIM21J301	0.9 $\pm$ 0.2	300	0.20	500
CIM21J471	0.9 $\pm$ 0.2	470	0.25	500
CIM21J601	0.9 $\pm$ 0.2	600	0.25	500
CIM21J751	0.9 $\pm$ 0.2	750	0.35	400
CIM21J102	0.9 $\pm$ 0.2	1000	0.35	500
CIM21J152	0.9 $\pm$ 0.2	1500(at 70MHz)	0.45	500
CIM21J182	0.9 $\pm$ 0.2	1800(at 70MHz)	0.45	500
CIM21J202	0.9 $\pm$ 0.2	2000(at 70MHz)	0.50	500
CIM21J222	0.9 $\pm$ 0.2	2200(at 70MHz)	0.70	300
CIM21J252	0.9 $\pm$ 0.2	2500(at 50MHz)	0.70	300
CIM21K152	0.9 $\pm$ 0.2	1500	0.45	300
CIM21K252	0.9 $\pm$ 0.2	2500	0.80	250
CIM21N560	0.9 $\pm$ 0.2	56	0.20	600
CIM21N700	0.9 $\pm$ 0.2	70	0.20	600
CIM21N121	0.9 $\pm$ 0.2	120	0.25	500
CIM21N241	0.9 $\pm$ 0.2	240	0.30	400

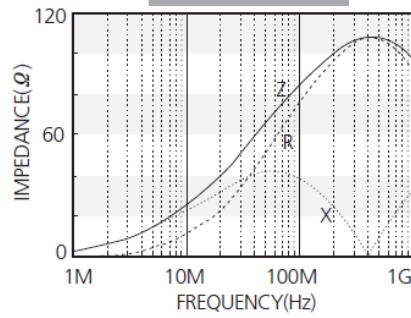
CHARACTERISTIC DATA



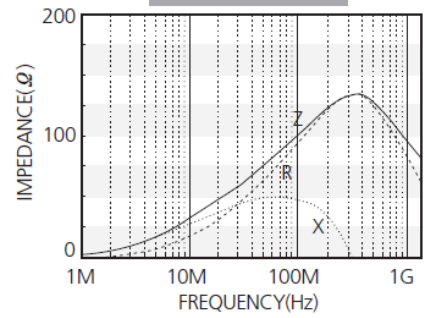
CIM21U600



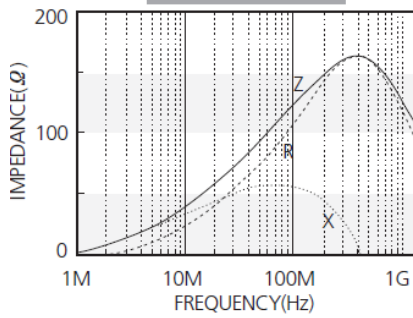
CIM21U800



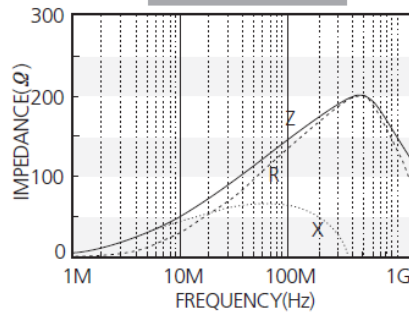
CIM21U101



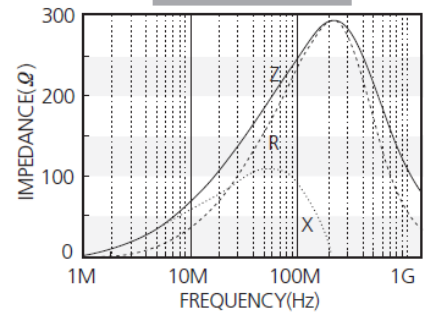
CIM21U121



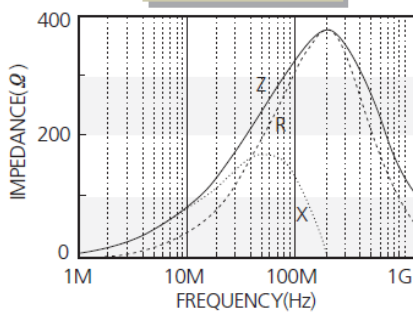
CIM21U151



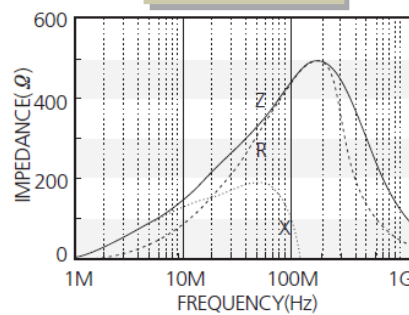
CIM21U241



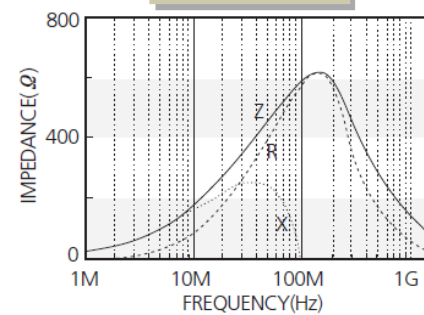
CIM21U301



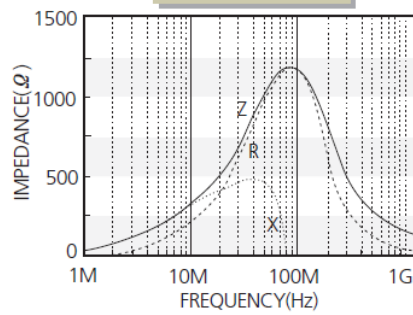
CIM21U471



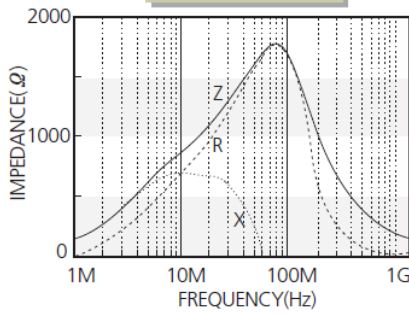
CIM21U601



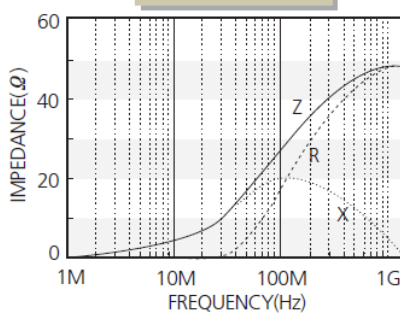
CIM21U102



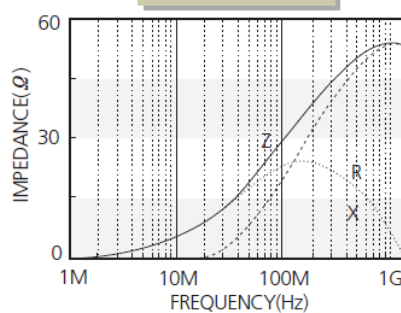
CIM21U202



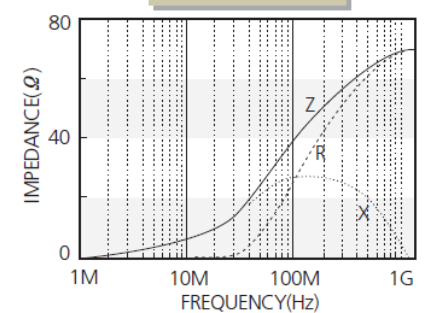
CIB21J260

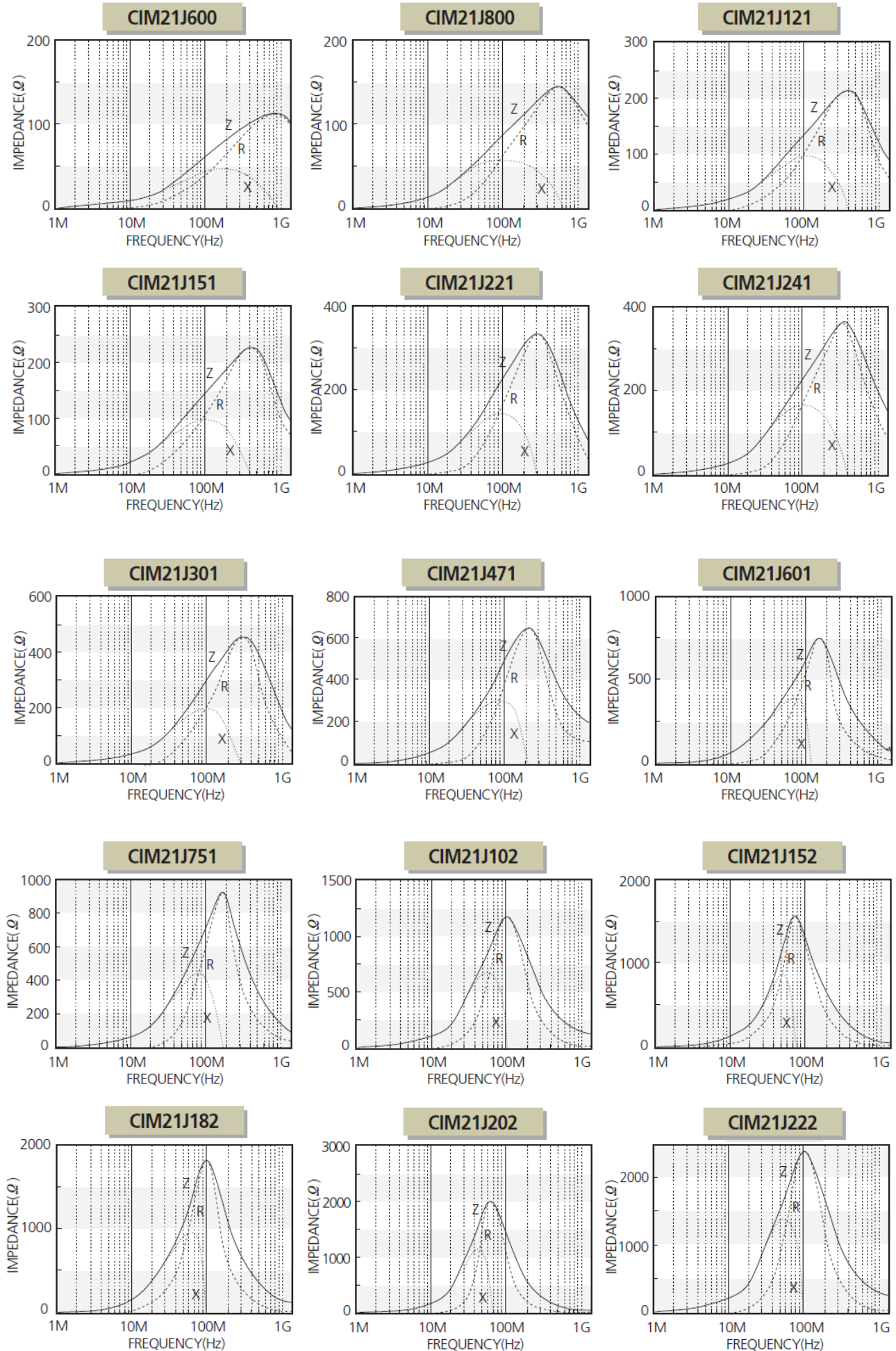


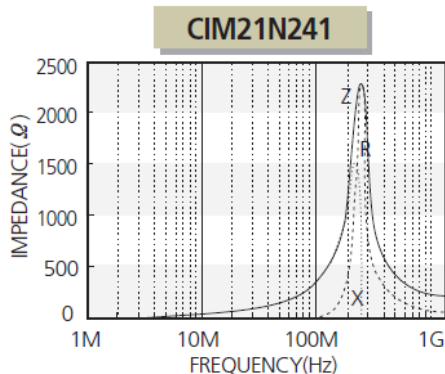
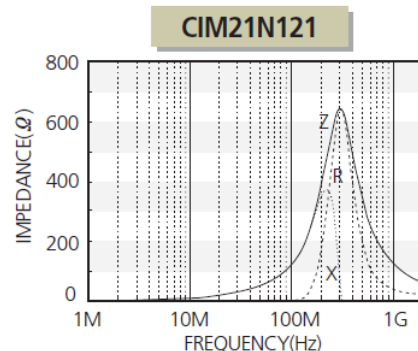
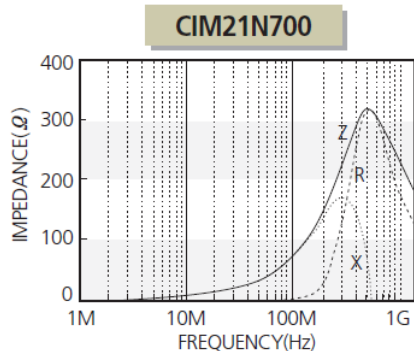
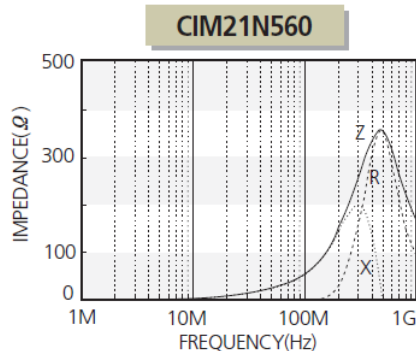
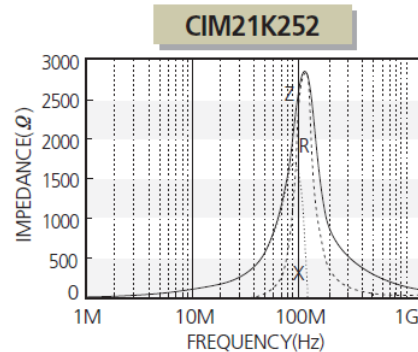
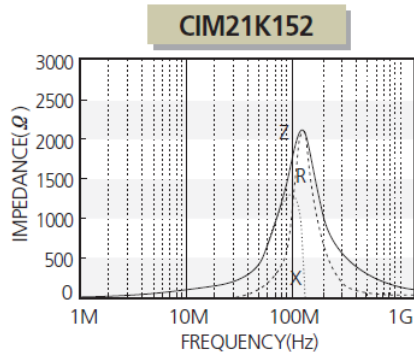
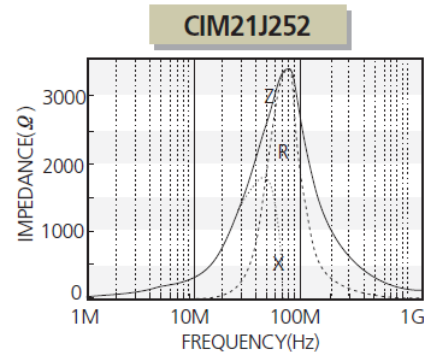
CIB21J300



CIB21J400







PRODUCT IDENTIFICATION

CI	M	21	U	121	N	E
(1)	(2)	(3)	(4)	(5)	(6)	(7)

(1) Chip Beads

(3) Dimension

(5) Nominal impedance (800:80Ω, 121:120Ω)

(6) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard)

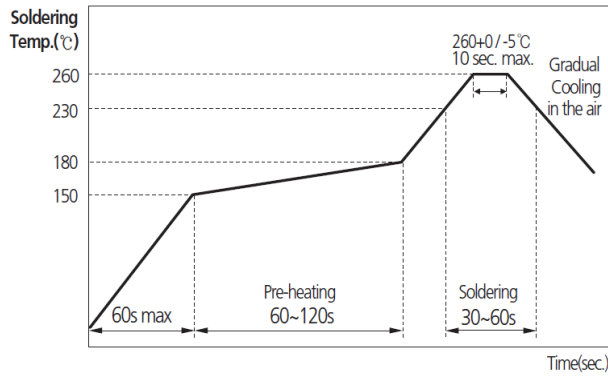
(7) Packaging(C:paper tape, E:embossed tape)

(2) M: Multi-layer type B:Mono-layer type

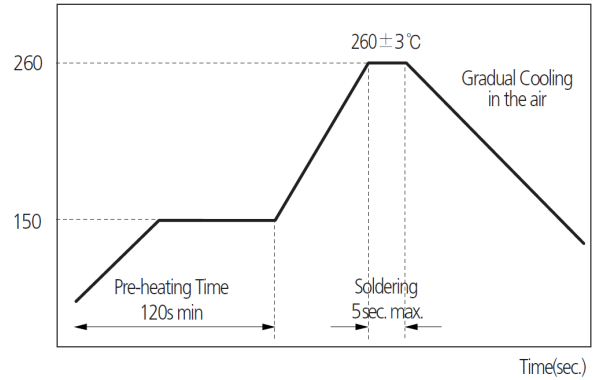
(4) Material Code

RECOMMENDED SOLDERING CONDITION

REFLOW SOLDERING



FLOW SOLDERING



PACKAGING

Packaging Style	Quantity(pcs/reel)
Embossed Taping	4,000



Any data in this sheet are subject to change, modify or discontinue without notice.

The data sheets include the typical data for design reference only. If there is any question regarding the data sheets, please contact our sales personnel or application engineers.